# FRIF IMI.

- Designed for WCDMA 3G IF Applications
- Excellent Size-to-Performance Ratio
- Balanced or Unbalanced Input and Output
- Hermetic 13.3 x 6.5 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)

#### Absolute Maximum Ratings

Rating	Value	Units	
Maximum Incident Power in Passband	+10	dBm	
Max. DC voltage between any 2 terminals	30	VDC	
Storage Temperature Range	-40 to +85	°C	
Suitable for lead-free soldering - Max. Soldering Profile	260°C for 30 s		



**SMP-53** 

SF1124A

### Electrical Characteristics

	Characteristic	Sym	Notes	Min	Тур	Max	Units
Nominal Center Frequency		f <sub>C</sub>	1		190.000		MHz
Passband	Insertion Loss at fc	IL			12	14.0	dB
	1 db Passband	BW <sub>1</sub>		4.6	5.1		MHz
	3 db Passband	BW3		5.1	5.7		
	Amplitude Ripple over fc±2.4 MHz		1, 2		.70	1.0	dB <sub>P-P</sub>
	Phase Linearity over fc±2.4 MHz		i F		4	10	°P-P
	Group Delay Variation over fc ±fc2.4 MHz	GDV			75	120	ns <sub>P-P</sub>
Rejection	fc-4.1 to fc-3.65 and fc+3.4 to fc+3.8 MHz			10			1
fc-5.0 to fc-4.1 and fc+3.8 to fc+5.0 MHz fc-10.0 to fc-5.0 and fc+5.0 to fc+10.0 MHz fc-20.0 to fc-10.0 and fc+10.0 to fc+20.0 MHz At 157.6 MHz At 165.7 MHz fc-60 MHz to fc-20 MHz			i F	30			
			i F	40			1
			1, 2, 3	40			dB
			1, 2, 3	40			uв
			i F	40			
			i F	40			
	fc+20 MHz to fc+60 MHz			40			
Part to Part Average Group Delay Variation						±5	nsec
Operating Temperature Range		Τ <sub>Α</sub>	1	-10	+25	+85	°C
Frequency Temperature Coefficient		FTC			-18		ppm/°C
Impedance Match	ning to 50Ω Unbalanced	External L-C					
Case Style		SMP-53 13.3 x 6.5 mm Nominal Footprint					
Lid Symbolization	n (YY = year, WW = week)	RFM SF1124A YYWW					

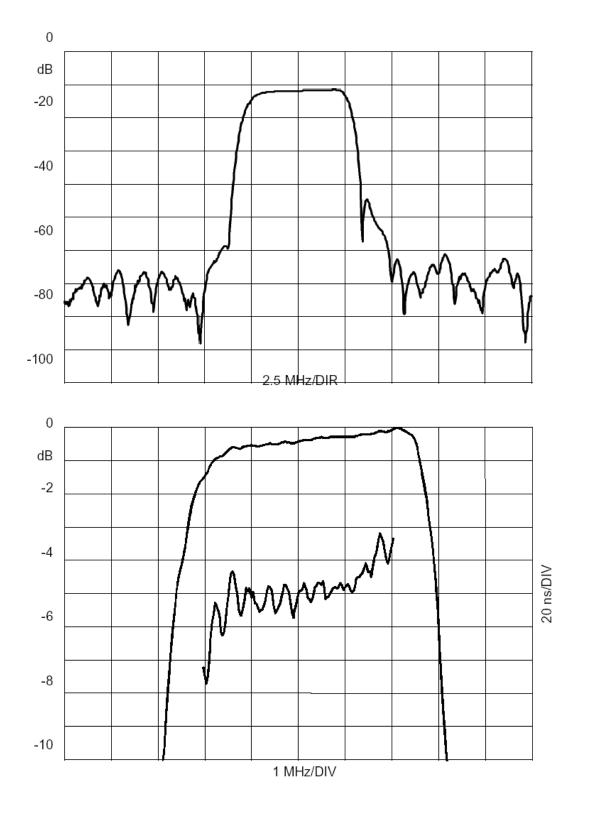
#### Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50  $\Omega$  and measured with 50  $\Omega$  network analyzer.

- 2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
- 3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
- 4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
- 5. The design, manufacturing process, and specifications of this filter are subject to change.
- 6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
- 7. US and international patents may apply.
- Electrostatic Sensitive Device. Observe precautions for handling.

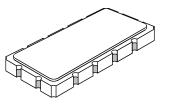
#### **Electrical Connections**

Connection	Terminals
Port 1 Hot	11
Port 1 Gnd Return	12
Port 2 Hot	5
Port 2 Gnd Return	6
Case Ground	All others



# SMP-53 Case

## 12-Terminal Ceramic Surface-Mount Case 13.3 x 6.5 mm Nominal Footprint



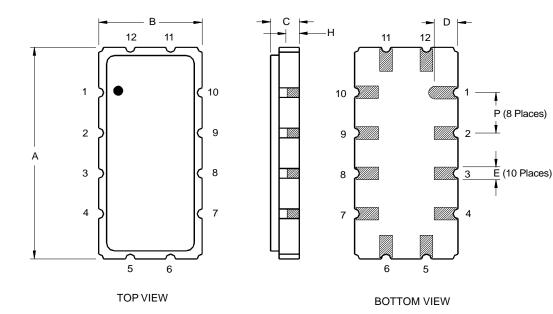
#### **Case Dimensions**

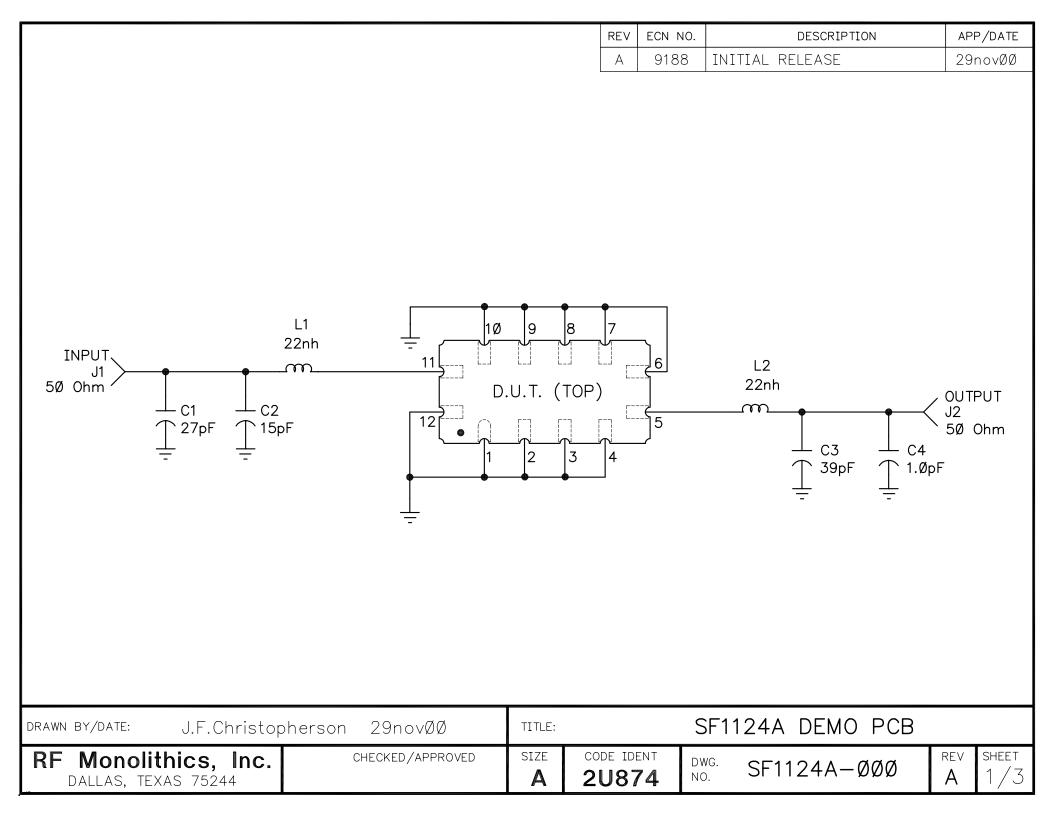
Dimension	mm			Inches		
Dimension	Min	Nom	Max	Min	Nom	Max
Α	13.08	13.31	13.60	0.515	0.524	0.535
В	6.27	6.50	6.80	0.247	0.256	0.268
С		1.91	2.00		0.075	0.079
D		1.50			0.059	
E		0.79			0.031	
н		1.0			0.039	
Р		2.54			0.100	

Materials				
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80- 200 ulnches (203-508 uM) Ni.			
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick			
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic			
Pb Free				

#### **Electrical Connections**

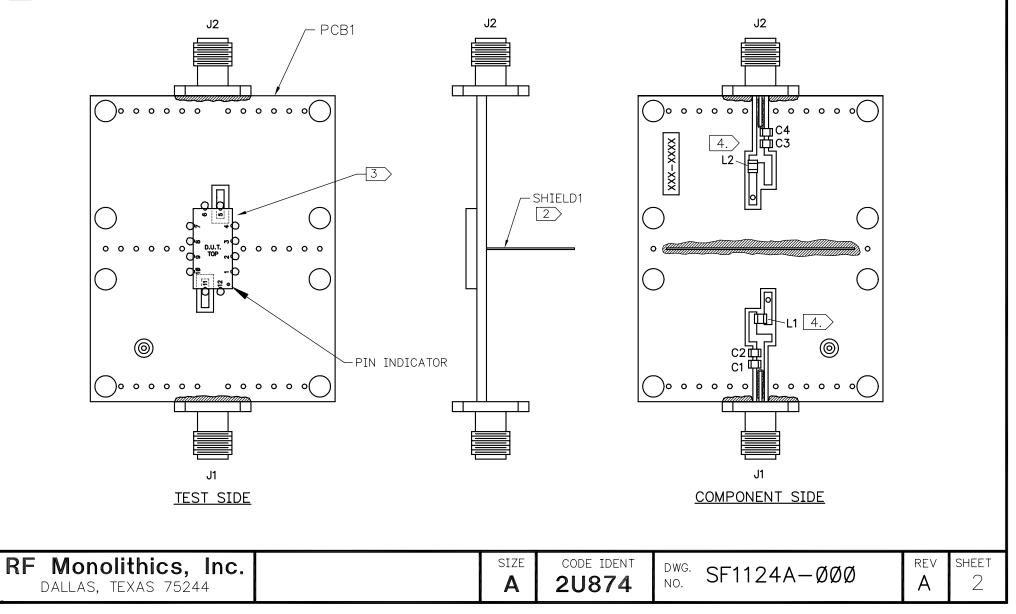
	Connection	Terminals		
Port 1 Input or Return		11		
	Return or Input	12		
Port 2	Output or Return	5		
	Return or Output	6		
	Ground	All others		
Single Ended Operation		Return is ground		
Differential Operation		Return is hot		

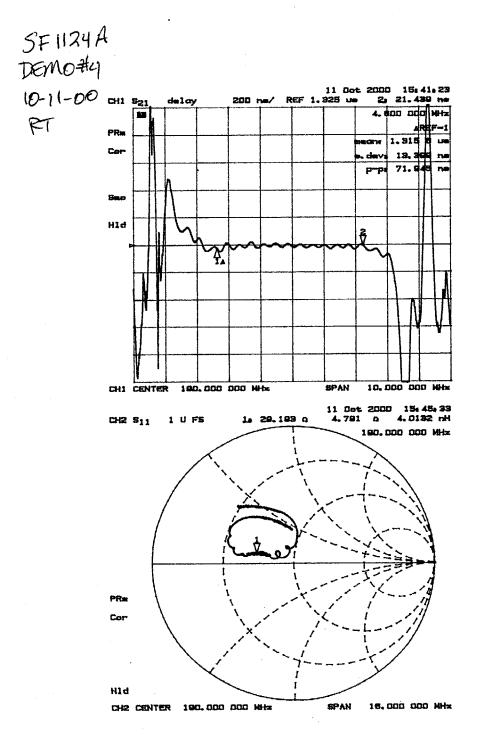


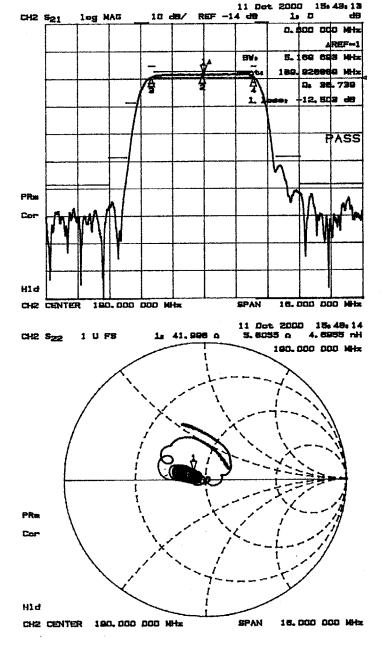


NOTES:

- 1. SOLDER MOUNT COMPONENTS & CONNECTORS TO PCB1.
- 2. SOLDER SHIELD1 AS SHOWN AND TRIM TAB FROM SHIELD SO THAT IT IS FLUSH WITH PCB.
- 3. ORIENT THE FLTR1 AND SOLDER IT DOWN TO THE BOARD AS SHOWN.
- 4. L1 AND L2 INDUCTORS ARE 90° TO EACH OTHER.







SF1124A-000

SHEET 3

C1= 2786 C7= 2286 C4= 1866

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L1, L2= 22nH